

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

MAIL STOP - PATENT APPLICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a patent application under 37 CFR 1.53(b).

22581 U.S. PTO
10/790077



Inventor(s): Shyan-Wei CHEN	Attorney Docket No.: 3095-131
Date Filed: March 2, 2004	Filed by: BHT/jlw
Title: FACEMASK HARNESS	

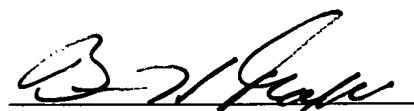
Transmitted herewith for filing are the following items:

1. Transmittal cover sheet for new U.S. Patent application.
2. 7 pages of specification, including claims and Abstract.
3. 3 claims.
4. 9 sheets of FORMAL drawings (Figs. 1-9).
5. Combined Oath/Declaration and Power of Attorney.
6. Request for Nonpublication Under 35 U.S.C. §122(b)(2)(B)(i).
7. A check in the amount of \$385.
8. Early Notification Serial No. Postcard.

THE FILING FEE IS CALCULATED AS FOLLOWS:				Basic Fee:	\$770.00
Total Claims:	3	- 20 =	0	X \$18 =	\$0.00
Independent Claims:	1	- 3 =	0	X \$86 =	\$0.00
Correspondence Address: TROXELL LAW OFFICE PLLC 5205 Leesburg Pike, Suite 1404 Falls Church, VA 22041 Phone: 703-575-2711 Fax: 703-575-2707				Multiple Dependent Claim (add \$290.00):	\$0.00
				Subtotal:	\$770.00
				50% Reduction if Small Entity Status:	\$385.00
				Total:	\$385.00

The Commissioner is hereby authorized to charge any additional fees associated with this communication, including patent application filing fees and processing fees under 37 CFR 1.16 and 37 CFR 1.17 or credit any overpayment to Deposit Account No. 501874.

Date: March 2, 2004


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**NONPUBLICATION REQUEST
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor Shyan-Wei Chen

Title Facemask Harness

Atty Docket Number _____

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

January 12, 2004

Date

Shyan-Wei Chen
Signature

Shyan-Wei Chen
Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

Burden Hour Statement: This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.